

Heat resistant masking tape based polyimide with strong adhesive force

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Feature

Heat resistant tape based Polyimide for solder-process

Have excellent performance to not only metal but also various resin.

Stable adhesion even at high temperature

We do not use 13 substances specified by VOC such as formaldehyde, acetaldehyde, toluene, etc. as constituent materials, as determined by guidelines for indoor air pollution

(Ministry of Health, Labor and Welfare).

Application

Fixation for electronics-parts or semiconductor chip parts

Fixation of parts

Fixation with water-proof

Structure



Polyethyleneterephthalate with release-treatment on surface

Special structure acrylic adhesive layer

Polyimide film as base

Properties

general properties

item	Thickness base layer (μm)	Thickness adhesive layer (mm)	Adhesive force SUS(25°C (N/inch)	Adhesive force SUS(200°C (MPa)
178	75	12.5	2.5	4.5

※Measure method
Adhesive force

Adhesive force JIS Z0237
PET#25 backing, peeling speed 300mm/min, 180° angle.

Precautions on use

All technical data are prepared based on the tests and measured values carried out in the laboratory of KGK Chemical Corp. as the standard.

However, product characteristics may vary greatly depending on environment and adherend.

Therefore, regarding these characteristic data, it is a reference value, not a guaranteed value.

Before using it please make sure that this product is suitable for the intended use and environment.

Caution on storage

Please be sure to put it in a box and keep it.

Please choose a cold and dark place not to be exposed to direct sunlight for the storage location.

In particular, please do not expose to high temperature and high humidity

(temperature 30 °C or more and humidity 50% or more forbidden).

The warranty period of the tape is unopened and it is six months after shipment.

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